



Initial Product/Process Change Notification

Document #: IPCN24650X

Issue Date: 19 Apr 2022

Title of Change:	Qualification of alternate site Aizu, Japan (JND) from current site Gresham, OR (USR) for onsemi ONC25HV wafer technology.
Proposed First Ship date:	26 Aug 2022 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or Scott.Brow@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < PCN.Support@onsemi.com >
Marking of Parts/ Traceability of Change:	Labels on boxes and reels will show "Diffused In: JP" for product produced out of Aizu, Japan. There is no changes to the marking of the actual units. Material from (2) different FABs cannot be combined into one reel.
Change Category:	Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Addition

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Aizu, Japan	None

Description and Purpose:

onsemi would like to inform customers of our intent to qualify our ONC25HV process technology into our Aizu, Japan (JND) FAB site. At the expiry of the FPCN, to be released later this year, the ONC25HV die used for the devices listed in this IPCN may be sourced from either FAB site. Note that some devices listed are dual die of different wafer technologies. This PCN only applies to the ONC25HV die of these dual die products.

	From	To
FAB Site	onsemi Gresham, OR (USR)	onsemi Aizu, Japan (JND) or onsemi Gresham, OR (USR)

There are no product marking changes as a result of this change.

Please see the Marking of Parts/Traceability of change to be able to identify the material with the change.



Initial Product/Process Change Notification

Document #: IPCN24650X

Issue Date: 19 Apr 2022

Qualification Plan:

QV DEVICE NAME : NCL2801CDADR2G

RMS# : 80476

PACKAGE : SOIC 8 PBF H

Test	Specification	Condition	Interval
HTOL	JA108	Ta= 125°C, 100 % max rated Vcc	1008 hrs.
HTSL	JA103	Ta= 150°C	1008 hrs.
PC	JA112 JA113	SMD only, Test @ 0 & EP	
SAT		Test pre- and post- PC	
ELFR	JA018	Ta= 125°C, 100 % max rated Vcc	48 hrs.
TC	JA104	Ta= -65°C to +150°C	500 cyc
uHAST	JA118	130°C, 85% RH, 18.8psig, unbiased	96 hrs.
HAST	JA110	130°C, 85% RH, 18.8psig, bias	96 hrs.
BS	AEC-Q100-001	Cpk >1.67, 30 bonds from 5units	
BPS	M883 Method 2011	3gm Pull Force Min	

QV DEVICE NAME : NCP13992ADDR2G

RMS# : 80474

PACKAGE : SOIC 16 LESS PIN 13 PBFH

Test	Specification	Condition	Interval
HTOL	JA108	Ta= 125°C, 100 % max rated Vcc	1008 hrs.
HTSL	JA103	Ta= 150°C	1008 hrs.
PC	JA112 JA113	SMD only, Test @ 0 & EP	
SAT		Test pre- and post- PC	
ELFR	JA018	Ta= 125°C, 100 % max rated Vcc	48 hrs.
TC	JA104	Ta= -65°C to +150°C	500 cyc
uHAST	JA118	130°C, 85% RH, 18.8psig, unbiased	96 hrs.
HAST	JA110	130°C, 85% RH, 18.8psig, bias	96 hrs.
BS	AEC-Q100-001	Cpk >1.67, 30 bonds from 5units	
BPS	M883 Method 2011	3gm Pull Force Min	

Estimated date for qualification completion: 29 July 2022

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
NCP1256ESN65T1G	NCL2801CDADR2G
NCP1256ASN100T1G	NCL2801CDADR2G
NCP1256ASN65T1G	NCL2801CDADR2G
NCP1256BSN65T1G	NCL2801CDADR2G
NCP1399AADR2G	NCP13992ACDR2G



Initial Product/Process Change Notification

Document #: IPCN24650X

Issue Date: 19 Apr 2022

NCP1399ACDR2G	NCP13992ACDR2G
NCP1399AFDR2G	NCP13992ACDR2G
NCP1399AGDR2G	NCP13992ACDR2G
NCP1399AHDR2G	NCP13992ACDR2G
NCP1399AIDR2G	NCP13992ACDR2G
NCP1399AMDR2G	NCP13992ACDR2G
NCP1399ANDR2G	NCP13992ACDR2G
NCP1399APDR2G	NCP13992ACDR2G
NCP1399ARDR2G	NCP13992ACDR2G
NCP1399ASDR2G	NCP13992ACDR2G
NCP1399ATDR2G	NCP13992ACDR2G
NCP1399BADR2G	NCP13992ACDR2G
NCL30086BHDR2G	NCL2801CDADR2G
NCL30185BDR2G	NCL2801CDADR2G
NCL30186BDR2G	NCL2801CDADR2G
NCL30186DDR2G	NCL2801CDADR2G
NCL30188ADR2G	NCL2801CDADR2G
NCL30188BDR2G	NCL2801CDADR2G
NCP13992AADR2G	NCP13992ACDR2G
NCP13992ABDR2G	NCP13992ACDR2G
NCP13992ACDR2G	NCP13992ACDR2G
NCP13992ADDR2G	NCP13992ACDR2G
NCP13992AEDR2G	NCP13992ACDR2G
NCP13992AFDR2G	NCP13992ACDR2G
NCP13992AGDR2G	NCP13992ACDR2G
NCP13992AHDR2G	NCP13992ACDR2G
NCP13992AJDR2G	NCP13992ACDR2G
NCP13992AKDR2G	NCP13992ACDR2G
NCP13992ALDR2G	NCP13992ACDR2G
NCP13992AMDR2G	NCP13992ACDR2G
NCP13992ANDR2G	NCP13992ACDR2G
NCP13992ARDR2G	NCP13992ACDR2G
NCP13992ASDR2G	NCP13992ACDR2G
NCP13992ATDR2G	NCP13992ACDR2G



Initial Product/Process Change Notification

Document #: IPCN24650X

Issue Date: 19 Apr 2022

NCP13992AUDR2G	NCP13992ACDR2G
NCP13992AWDR2G	NCP13992ACDR2G
NCL2801CDADR2G	NCL2801CDADR2G
NCL2801CDBDR2G	NCL2801CDADR2G
NCL2801CFADR2G	NCL2801CDADR2G
NCP1615C4DR2G	NCL2801CDADR2G
NCP1615C5DR2G	NCL2801CDADR2G
NCP1616A1DR2G	NCL2801CDADR2G
NCP1616A2DR2G	NCL2801CDADR2G
NCP1342BMDCCDD1R2G	NCL2801CDADR2G
NCP1343BADBDEAD1R2G	NCL2801CDADR2G
NCP1342ENACEFD1R2G	NCL2801CDADR2G
NCP1343ENAAEBBD1R2G	NCL2801CDADR2G
NCP1340B7D1R2G	NCL2801CDADR2G
NCP1340B8D1R2G	NCL2801CDADR2G
NCP1341B5D1R2G	NCL2801CDADR2G
NCP1340B3D1R2G	NCL2801CDADR2G
NCP1340B4D1R2G	NCL2801CDADR2G
NCP1340B5D1R2G	NCL2801CDADR2G
NCP1340B9D1R2G	NCL2801CDADR2G
NCP1341A1D1R2G	NCL2801CDADR2G
NCP1341B1D1R2G	NCL2801CDADR2G
NCP1341B4D1R2G	NCL2801CDADR2G
NCP1342AMDADGD1R2G	NCL2801CDADR2G
NCP1342AMDCDAD1R2G	NCL2801CDADR2G
NCP1342ANACCED1R2G	NCL2801CDADR2G
NCP1342BMDCDAD1R2G	NCL2801CDADR2G
NCP1342BMDCDD1R2G	NCL2801CDADR2G
NCP1342ENDCEAD1R2G	NCL2801CDADR2G
NCP1343AMDCDBD1R2G	NCL2801CDADR2G
NCP1343FNAAABCD1R2G	NCL2801CDADR2G
NCP1342AMAACD1R2G	NCL2801CDADR2G
NCP1342AMDCDD1R2G	NCL2801CDADR2G
NCP1342AMDCDHD1R2G	NCL2801CDADR2G



Initial Product/Process Change Notification

Document #: IPCN24650X

Issue Date: 19 Apr 2022

NCP1342ANACED1R2G	NCL2801CDADR2G
NCP1342ANDAAD1R2G	NCL2801CDADR2G
NCP1342ANDBDD1R2G	NCL2801CDADR2G
NCP1342BKDCDAD1R2G	NCL2801CDADR2G
NCP1342DADBDD1R2G	NCL2801CDADR2G
NCP1342AMDCCDR2G	NCL2801CDADR2G
NCP1342DADBBDGD1R2G	NCL2801CDADR2G